

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

- Claim 1 (Original) A unitary spring contact probe comprising a resilient spring section, a first plunger section extending from a distal end of the resilient spring section for contacting a semiconductor device under test and a first stopper projecting from the first plunger section substantially transversely to an axial direction of the plunger section;
- wherein the resilient spring section, the first plunger section, and the first stopper are formed as an integral, unitary structure.
- Claim 2 (Original) The spring contact probe as claimed in claim 1, wherein the probe is formed from a wire-like material.
- Claim 3 (Currently Amended) The spring contact probe as claimed in claim 1, including a second plunger section at a proximal ~~another distal~~ end of the resilient spring section that is opposite the first plunger section.
- Claim 4 (Original) The spring contact probe as claimed in claim 3, wherein the second plunger section extends out of the spring section in a substantially straight line in the same general axial direction as the spring section.
- Claim 5 (Currently Amended) The spring contact probe as claimed in claim 4, wherein the second plunger section extends substantially parallel to the first plunger section when the spring section is uncompressed.

- Claim 6 (Currently Amended) The spring contact probe as claimed in claim 3, wherein the first plunger section and the second plunger section lie on opposite sides of an axial plane passing perpendicularly through a center of the spring section.
- Claim 7 (Currently Amended) The spring contact probe as claimed in claim 3, wherein the first plunger section and the second plunger section are fashioned from a single strip of material.
- Claim 8 (Original) The spring contact probe as claimed in claim 3, including a second stopper projecting from the second plunger section substantially transversely to an axial direction of the second plunger section.
- Claim 9 (Currently Amended) ~~The spring contact probe as claimed in claim 1;~~ A unitary spring contact probe comprising a resilient spring section, a first plunger section extending from a distal end of the resilient spring section for contacting a semiconductor device under test and a first stopper projecting from the first plunger section substantially transversely to an axial direction of the plunger section;
wherein the first stopper is configured with a sufficiently large surface area so as to act as a thermal device for facilitating the dissipation of heat from the spring contact probe.
- Claim 10 (Currently Amended) The spring contact probe as claimed in claim 1, wherein the spring section, the first plunger section and the first stopper are fashioned from a single strip of material.
- Claim 11 (Original) The spring contact probe as claimed in claim 1, wherein the spring contact probe is made from copper or beryllium copper.

- Claim 12 (Original) The spring contact probe as claimed in claim 11, wherein the spring contact probe is plated with a material selected from the group consisting of nickel, palladium, hard gold and rhodium.
- Claim 13 (Currently Amended) An apparatus for testing a semiconductor device comprising:
- a plurality of unitary spring contact probes each comprising a resilient spring section, a first plunger section extending from a distal end of the resilient spring section for contacting a semiconductor device under test and a first stopper projecting from the first plunger section substantially transversely to an axial direction of the plunger section; wherein the resilient spring section, the first plunger section, and the first stopper are formed as an integral, unitary structure;
 - one or more insulative guiding holders for mounting the spring contact probes; and
 - a retainer mechanism coupled to the first stoppers of the spring contact probes for securing the spring contact probes to the insulative guiding holders.
- Claim 14 (Currently Amended) The apparatus as claimed in claim 13, wherein the retainer mechanism comprises a retainer plate including holes that allow the first plunger sections of the spring contact probes to protrude from a surface of the retainer plate for contacting the semiconductor device.
- Claim 15 (Original) The apparatus as claimed in claim 13, including cavities in the insulative guiding holders for introducing purging air onto the spring contact probes.
- Claim 16 (Currently Amended) The apparatus as claimed in claim 13, including an electrical circuit contacted by an end of the spring contact probe that is opposite

the first plunger section, wherein the electrical circuit is coupled to signal processing resources of the apparatus.

Claim 17 (Currently Amended) The apparatus as claimed in claim 16, including a second plunger section at ~~said~~ the end of the resilient spring section that is opposite the first plunger section for contacting the electrical circuit.

Claim 18 (Currently Amended) The apparatus as claimed in claim 17, including a second retaining mechanism coupled to ~~another~~ a second stopper of each of the spring contact probes projecting from the second plunger ~~sections~~ section for securing the spring contact probes to the insulative guiding holders.

Claim 19 (Currently Amended) The apparatus as claimed in claim 18, wherein the second retaining mechanism comprises a retainer plate including holes that allow the second plunger ~~sections~~ section of the spring contact ~~probes~~ probe to protrude from a surface of the second retainer plate for contacting the electrical circuit.